



## HIGH IP<sub>3</sub>, LOW NOISE AMPLIFIER, 0.2 - 4.0 GHz

### Typical Applications

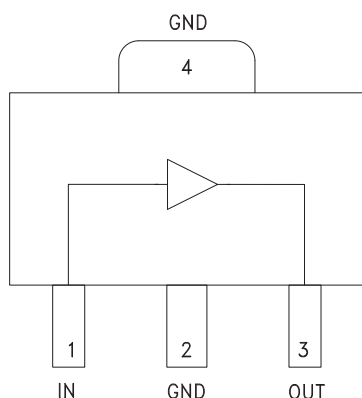
The HMC639ST89(E) is ideal for:

- Cellular / PCS / 3G
- WiMAX, WiBro, & Fixed Wireless
- CATV & Cable Modem
- Microwave Radio
- IF and RF Sections

### Features

- Low Noise Figure: 2.3 dB
- High P<sub>1dB</sub> Output Power: +22 dBm
- High Output IP<sub>3</sub>: +38 dBm
- Gain: 13 dB
- 50 Ohm I/O's - No External Matching
- Industry Standard SOT89 Package

### Functional Diagram



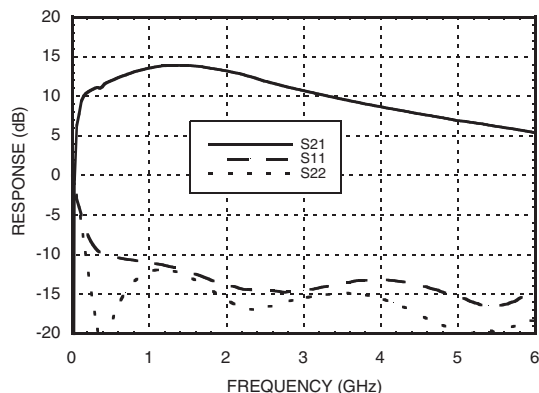
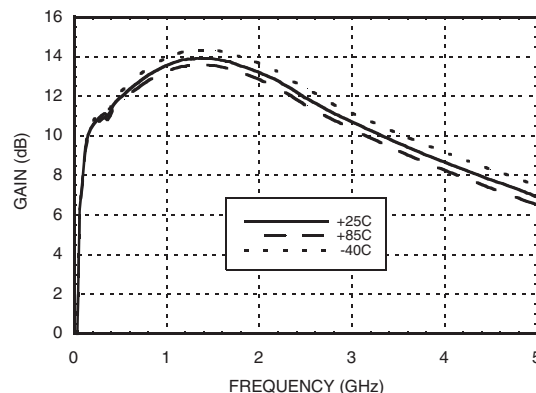
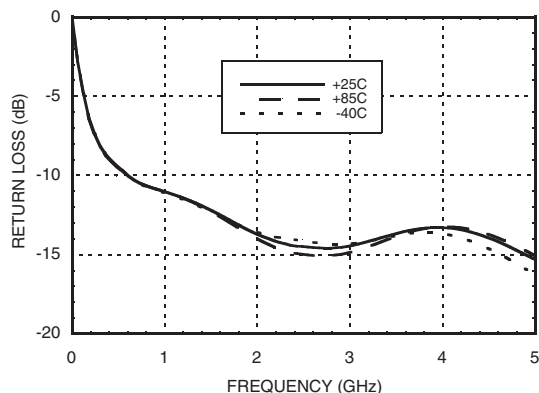
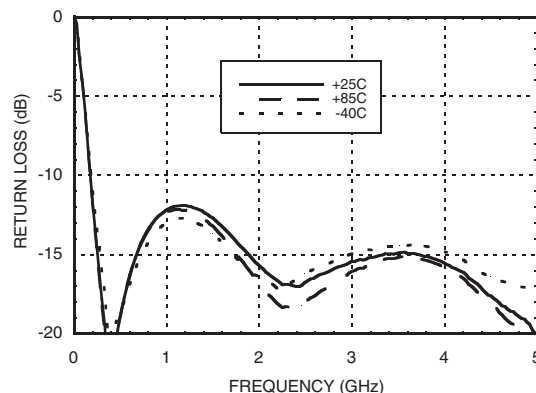
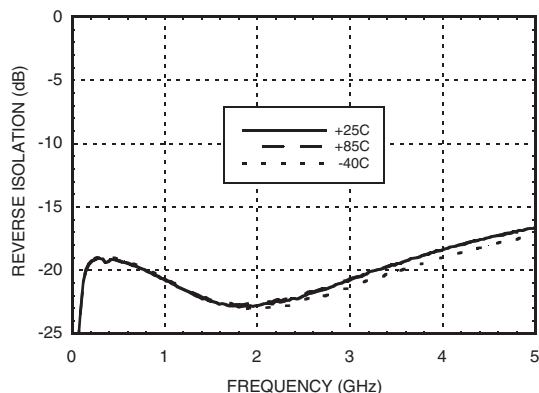
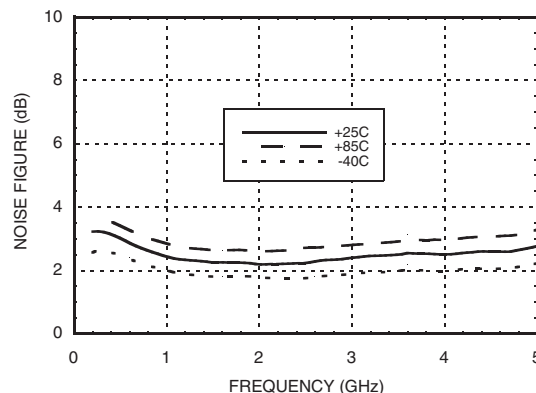
### General Description

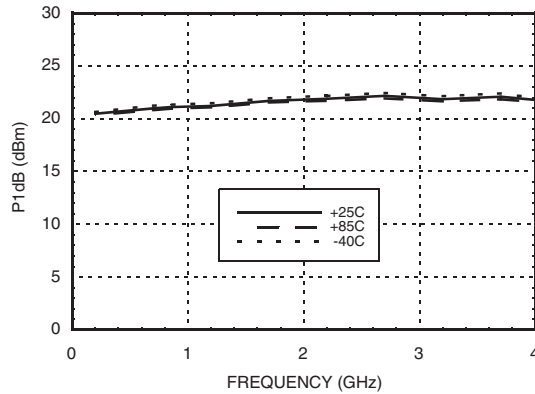
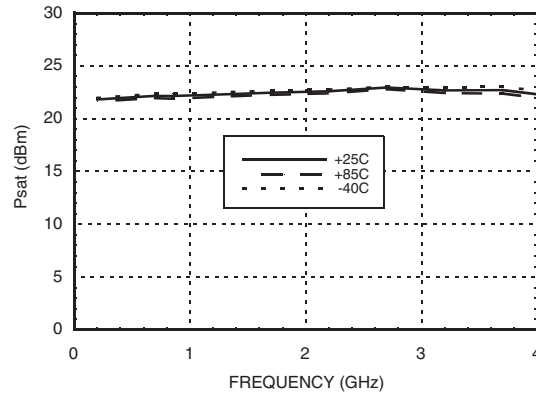
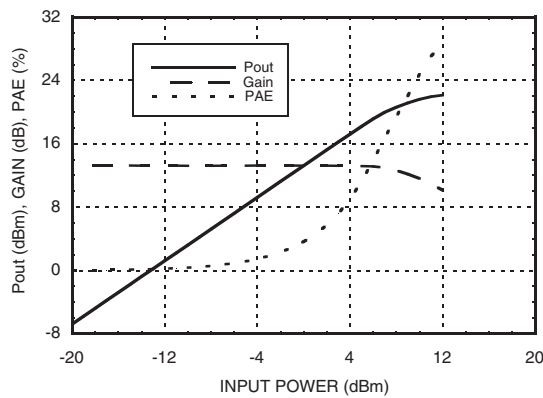
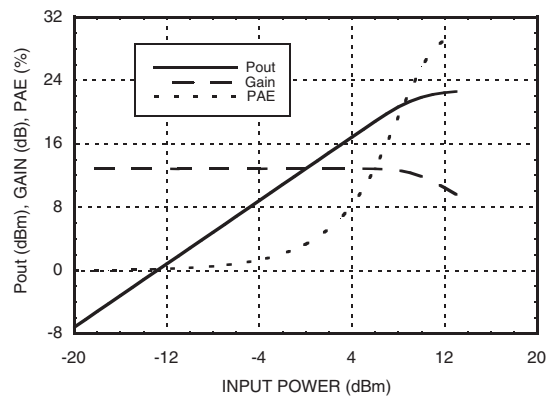
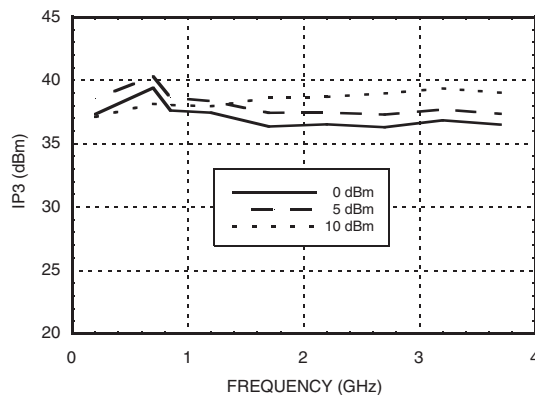
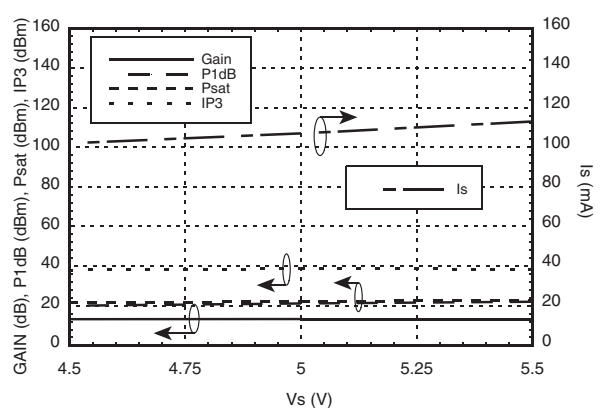
The HMC639ST89(E) is a GaAs pHEMT, High Linearity, Low Noise, Wideband Gain Block Amplifier covering 0.2 to 4.0 GHz. Packaged in an industry standard SOT89, the amplifier can be used as either a cascadable 50 Ohm gain stage, a PA Pre-Driver, a Low Noise Amplifier, or a Gain Block with up to +22 dBm output power. This versatile Gain Block Amplifier is powered from a single +5V supply and requires no external matching components. The internally matched topology permits this amplifier to be readily ported between virtually any printed circuit board material, regardless of its dielectric constant, thickness, or composition.

### Electrical Specifications, $V_s = 5V$ , $T_A = +25^\circ C$

| Parameter                                             | Min       | Typ. | Max  | Min.      | Typ. | Max. | Units  |
|-------------------------------------------------------|-----------|------|------|-----------|------|------|--------|
| Frequency Range                                       | 0.7 - 2.2 |      |      | 0.2 - 4.0 |      |      | GHz    |
| Gain                                                  | 10        | 13   |      | 6         | 10   |      | dB     |
| Gain Variation Over Temperature                       |           | 0.01 | 0.02 |           | 0.01 | 0.02 | dB/ °C |
| Input Return Loss                                     |           | 12   |      |           | 12   |      | dB     |
| Output Return Loss                                    |           | 12   |      |           | 14   |      | dB     |
| Reverse Isolation                                     |           | 20   |      |           | 20   |      | dBm    |
| Output Power for 1 dB Compression (P <sub>1dB</sub> ) | 19        | 21   |      | 20        | 22   |      | dB     |
| Output Third Order Intercept (IP <sub>3</sub> )       | 35        | 38   |      | 35        | 38   |      | dBm    |
| Noise Figure                                          |           | 2.3  |      |           | 2.5  |      | dB     |
| Supply Current (I <sub>cc</sub> )                     | 90        | 110  | 120  | 90        | 110  | 120  | mA     |

Note: Data taken with broadband bias tee on device output.

**Broadband Gain & Return Loss**

**Gain vs. Temperature**

**Input Return Loss vs. Temperature**

**Output Return Loss vs. Temperature**

**Reverse Isolation vs. Temperature**

**Noise Figure vs. Temperature**


**P<sub>1dB</sub> vs. Temperature**

**P<sub>sat</sub> vs. Temperature**

**Power Compression @ 850 MHz**

**Power Compression @ 2200 MHz**

**Output IP<sub>3</sub> vs. Output Tone Power**

**Gain, Power, Output IP<sub>3</sub> & Supply Current vs. Supply Voltage @ 850 MHz**




**HIGH IP<sub>3</sub>, LOW NOISE  
AMPLIFIER, 0.2 - 4.0 GHz**

## Absolute Maximum Ratings

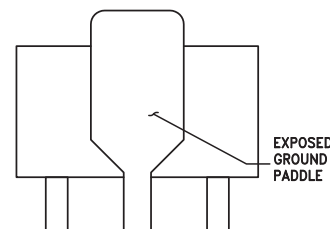
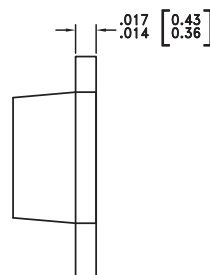
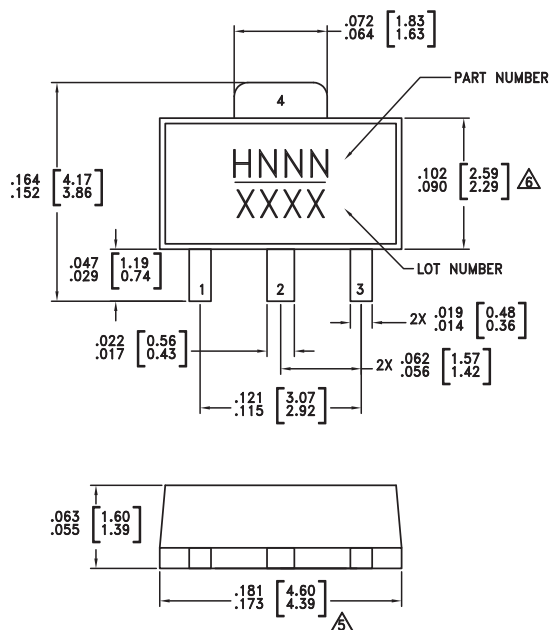
|                                                                             |                |
|-----------------------------------------------------------------------------|----------------|
| Collector Bias Voltage (Vcc)                                                | +5.5 Volts     |
| RF Input Power (RFIN)(Vcc = +5 Vdc)                                         | +15 dBm        |
| Channel Temperature                                                         | 150 °C         |
| Continuous P <sub>diss</sub> (T = 85 °C)<br>(derate 13.3 mW/°C above 85 °C) | 0.86 W         |
| Thermal Resistance<br>(Channel to lead)                                     | 75.6 °C/W      |
| Storage Temperature                                                         | -65 to +150 °C |
| Operating Temperature                                                       | -40 to +85 °C  |
| ESD Sensitivity (HBM)                                                       | Class 1A       |



**ELECTROSTATIC SENSITIVE DEVICE  
OBSERVE HANDLING PRECAUTIONS**

9

## Outline Drawing



### NOTES:

1. PACKAGE BODY MATERIAL:  
MOLDING COMPOUND MP-180S OR EQUIVALENT.
2. LEAD MATERIAL: Cu w/ Ag SPOT PLATING.
3. LEAD PLATING: 100% MATTE TIN.
4. DIMENSIONS ARE IN INCHES [MILLIMETERS]
5. DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
6. DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
7. ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.

## Package Information

| Part Number | Package Body Material                              | Lead Finish   | MSL Rating          | Package Marking <sup>[3]</sup> |
|-------------|----------------------------------------------------|---------------|---------------------|--------------------------------|
| HMC639ST89  | Low Stress Injection Molded Plastic                | Sn/Pb Solder  | MSL1 <sup>[1]</sup> | H639<br>XXXX                   |
| HMC639ST89E | RoHS-compliant Low Stress Injection Molded Plastic | 100% matte Sn | MSL1 <sup>[2]</sup> | <u>H639</u><br>XXXX            |

[1] Max peak reflow temperature of 235 °C

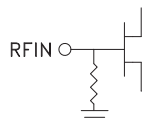
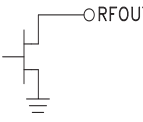
[2] Max peak reflow temperature of 260 °C

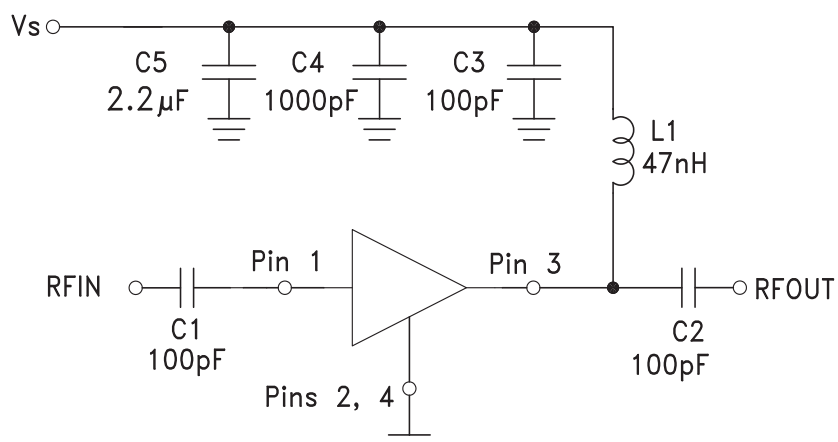
[3] 4-Digit lot number XXXX

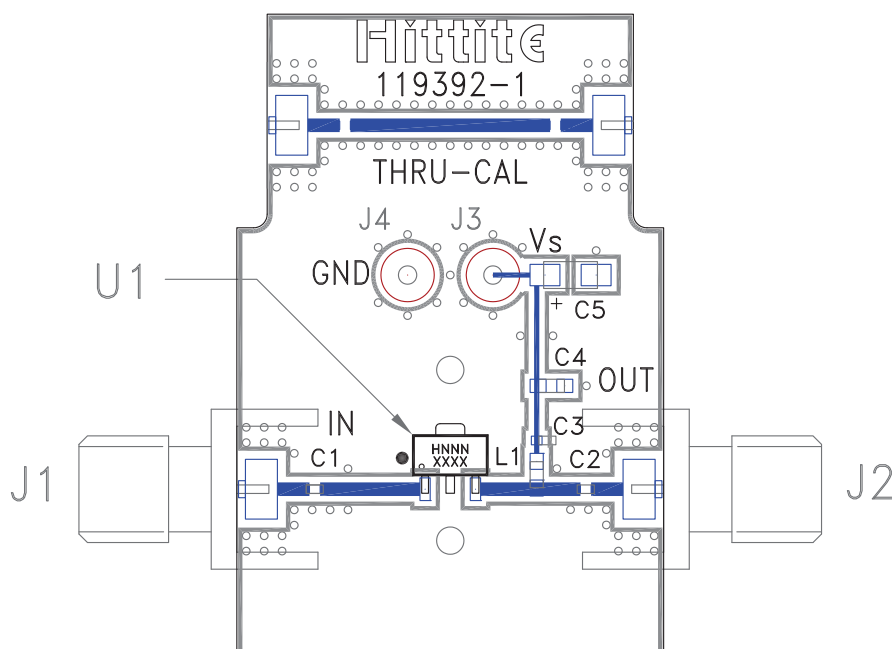
Information furnished by Analog Devices is believed to be accurate and reliable. However, no responsibility is assumed by Analog Devices for its use, nor for any infringements of patents or other rights of third parties that may result from its use. Specifications subject to change without notice. No license is granted by implication or otherwise under any patent or patent rights of Analog Devices. Trademarks and registered trademarks are the property of their respective owners.

For price, delivery, and to place orders: Analog Devices, Inc.,  
One Technology Way, P.O. Box 9106, Norwood, MA 02062-9106  
Phone: 781-329-4700 • Order online at [www.analog.com](http://www.analog.com)  
Application Support: Phone: 1-800-ANALOG-D


**HIGH IP<sub>3</sub>, LOW NOISE  
AMPLIFIER, 0.2 - 4.0 GHz**
**Pin Descriptions**

| Pin Number | Function | Description                                                                               | Interface Schematic                                                                 |
|------------|----------|-------------------------------------------------------------------------------------------|-------------------------------------------------------------------------------------|
| 1          | RFIN     | This pin is DC coupled. An off-chip DC blocking capacitor is required.                    |  |
| 3          | RFOUT    | RF Output and DC BIAS for the amplifier. See Application Circuit for off-chip components. |  |
| 2, 4       | GND      | These pins and package bottom must be connected to RF/DC ground.                          |  |

**Application Circuit**


**Evaluation PCB**

**List of Materials for Evaluation PCB 119394 <sup>[1]</sup>**

| Item               | Description                     |
|--------------------|---------------------------------|
| J1 - J2            | PCB Mount SMA Connector         |
| J3 - J4            | DC Pin                          |
| C1 - C3            | 100 pF Capacitor, 0402 Pkg.     |
| C4                 | 1000 pF Capacitor, 0603 Pkg.    |
| C5                 | 2.2 $\mu$ F Capacitor, Tantalum |
| L1                 | 47 nH Inductor, 0603 Pkg.       |
| U1                 | HMC639ST89(E)                   |
| PCB <sup>[2]</sup> | 119392 Evaluation PCB           |

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: FR4

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and package bottom should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation board should be mounted to an appropriate heat sink. The evaluation circuit board shown is available from Hittite upon request.